IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.							
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					ion		
upplier Infor		-											
Company name* Company unique ID				Unique ID Authority					Response Date*				
nsemi									2024-04-20				
Contact Name		Title - Conta	Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stev	wards	Product Env	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
uthorized Repre	esentative*	Title - Repre	Title - Representative			Phone - Representative*				Email - Representative*			
Product-Env-Stewards Product Enviro			iro Compliance		NA Product-Env-Stewards@onsemi.com					m			
Reques	ster Item Number	Mfr Item Number	Number Mfr Item Name			Effective Date	Version	N	Manufacturing Site	W	eight*	UOM	Unit Type
		ASX340AT2C00XPE D0-DRBR-E	VGA 1/4 SOC			2024-04-20		N	ЛҮ1	10	8.93	mg	Each
I anufacturing	g Proccess Informatio	on											
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020			J-STD-020 MSI	L Rating	Peak Proce	ess Body T	emperatur	e Max Time at Peak	Temperatui	e Numb	er of Reflow Cyc	les	
SnAgCu CU A		CU Alloy		3		260		C	30	seconds	3		
omments													
ITENTION: M	SL 3 Rated item requires B	Bake and Dry Pack (afte	r electrical test)										
or more informa	tion regarding material co	mposition please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	23.9	mg		Misc.	proprietary data		0.0908	mg
			Supplier	Silicon (Si)	7440-21-3		23.5726	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2366	mg
Die Attach	2.2	mg		Bismaleimide Monomer	proprietary data		0.847	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.011	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.22	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.011	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.22	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.22	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.011	mg
			Supplier	Other Additive Agents	Proprietary Data		0.44	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.22	mg
Imaging Lens	29.31	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5426	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5426	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5426	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.1545	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5426	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5426	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.4426	mg
Lid Attach	1.52	mg	Supplier	2,2-Bis(glycidyloxyphenyl)propane polymer	25085-99-8		0.38	mg
			Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		1.102	mg
			Supplier	Misc.	Proprietary Data		0.038	mg
Mold Compound	8.1	mg		Epoxy resin	proprietary data		2.0088	mg
			Supplier	Other Additive Agents	Proprietary Data		0.2592	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.81	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.779	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.243	mg
Solder Ball	24.55	mg	Supplier	Silver (Ag)	7440-22-4		0.7365	mg

			Supplier	Tin (Sn)	7440-31-5	23.6907	mg
			Supplier	Copper (Cu)	7440-50-8	0.1227	mg
Solder Mask	2.06	mg		Epoxy resin	proprietary data	0.2472	mg
			Supplier	Acrylate	Proprietary Data	0.7869	mg
			Supplier	Talc	14807-96-6	0.0556	mg
			Supplier	Miscellaneous	Trade Secret	0.0762	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	0.894	mg
Substrate Copper Foil	1.59	mg	Supplier	Copper (Cu)	7440-50-8	1.59	mg
Substrate - Core Material	7.88	mg		Epoxy resin	proprietary data	1.7076	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	6.1724	mg
Substrate Plating-Au	0.14	mg	Supplier	Gold (Au)	7440-57-5	0.14	mg
Substrate Plating-Cu	7.1	mg	Supplier	Copper (Cu)	7440-50-8	7.1	mg
Substrate Plating-Ni	0.33	mg	В	Nickel (Ni)	7440-02-0	0.33	mg
Wire Bond - Au	0.25	mg	Supplier	Gold (Au)	7440-57-5	0.25	mg